

S/N 10/789,882



PATENT

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Paul A. Farrar	Examiner:	Dao H Nguyen
Serial No.:	10/789,882	Group Art Unit:	2818
Filed:	February 27, 2004	Docket:	303.673US3
Title:	INTEGRATED CIRCUIT AND SEED LAYERS		

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicant respectfully requests that this Supplemental Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicant requests that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicant with the next official communication.

Pursuant to 37 C.F.R. §1.97(c)(2), Applicants have included the fee of \$180.00 as set forth in 37 C.F.R. §1.17(p). Please charge any additional fees or credit any overpayment to Deposit Account No. 19-0743.

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SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

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The Examiner is invited to contact the Applicant's Representative at the below-listed telephone number if there are any questions regarding this communication.

The present application is either a U.S. national patent application filed after June 30, 2003 or an international application that entered the national stage under 35 U.S.C. § 371 after June 30, 2003. Thus, Applicant believes that the U.S. Patent & Trademark Office has waived the requirement under 37 C.F.R. 1.98 (a)(2)(i) for submitting a copy of each cited U.S. patent and each U.S. patent application publication. The waiver is provided in a pre-OG notice from the U.S. Patent & Trademark Office entitled "Information Disclosure Statements May Be Filed Without Copies of U.S. Patents and Published Applications in Patent Applications filed after June 30, 2003" and dated July 11, 2003. Applicant acknowledges the requirement to submit copies of foreign patent documents and non-patent literature in accordance with 37 C.F.R. 1.98(a)(2).

Respectfully submitted,

PAUL A. FARRAR

By his Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
P.O. Box 2938
Minneapolis, MN 55402
(612) 371-2157

Date 7 December 2004

By David R. Cochran
David R. Cochran
Reg. No. 46,632

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: MS Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 7 day of December, 2004.

Name

KACIA LEE

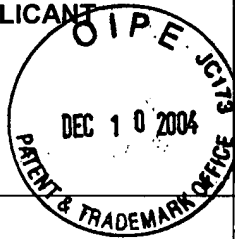
Signature

Kacia Lee

Substitute for form 1449A/PTO

**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**

(Use as many sheets as necessary)



Complete if Known

Application Number	10/789,882
Filing Date	February 27, 2004
First Named Inventor	Farrar, Paul
Group Art Unit	2818
Examiner Name	Nguyen, Dao

Sheet 1 of 1

Attorney Docket No: 303.673US3

US PATENT DOCUMENTS

Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Filing Date if Appropriate
	US-5,937,320	08/10/1999	Andricacos, P. C., et al.	04/08/1998
	US-6,103,320	08/15/2000	Matsumoto, S., et al.	06/09/1998
	US-6,208,016	03/27/2001	Farrar, Paul	02/24/1999
	US-6,245,662	06/12/2001	Naik, M., et al.	07/23/1998
	US-6,288,442	09/11/2001	Farrar, Paul A.	09/10/1998
	US-6,358,849	03/19/2002	Havemann, R. H., et al.	12/21/1999
	US-6,552,432	04/22/2003	Farrar, Paul A.	08/30/2001
	US-6,614,099	09/02/2003	Farrar, Paul A.	09/04/2001
	US-6,743,716	06/01/2004	Farrar, Paul A.	07/16/2002
	US-6,756,298	06/29/2004	Ahn, Kie Y., et al.	08/01/2002

FOREIGN PATENT DOCUMENTS

Examiner Initials*	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	T ²
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OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS

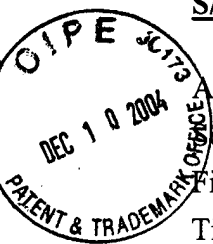
Examiner Initials*	Cite No ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
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EXAMINER

DATE CONSIDERED

Substitute Disclosure Statement Form (PTO-1449)

* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. ¹ Applicant's unique citation designation number (optional) ² Applicant is to place a check mark here if English language Translation is attached



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Title: INTEGRATED CIRCUIT AND SEED LAYERS

COMMUNICATION CONCERNING RELATED APPLICATION(S)

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Applicant would like to bring to the Examiner's attention the following related application(s) in the above-identified patent application:

<u>Serial/Patent No.</u>	<u>Filing Date</u>	<u>Attorney Docket</u>	<u>Title</u>
10/854552	May 26, 2004	303.664US5	STRUCTURES AND METHODS TO ENHANCE COPPER METALLIZATION
10/929251	August 30, 2004	303.672US2	SELECTIVE ELECTROLESS-PLATED COPPER METALLIZATION
10/931541	August 31, 2004	303.648US2	METHODS FOR MAKING INTEGRATED-CIRCUIT WIRING FROM COPPER, SILVER, GOLD, AND OTHER METALS

Respectfully submitted,
PAUL A. FARRAR

By Applicant's Representatives,
SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
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Date 7 December 2004

By

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KACIA LEE
Name

Kacia Lee
Signature